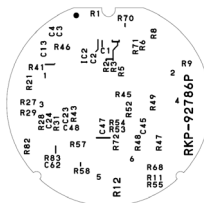
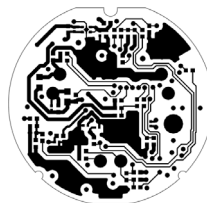
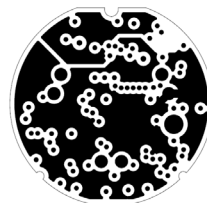
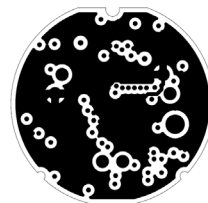
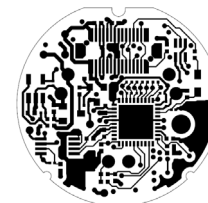


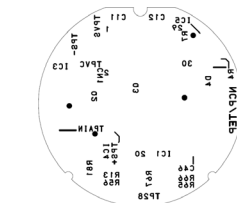
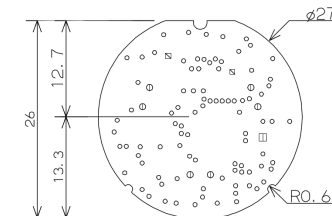
RKP-92786P

SILK PRINT FOR
PARTS SIDE

PARTS SIDE

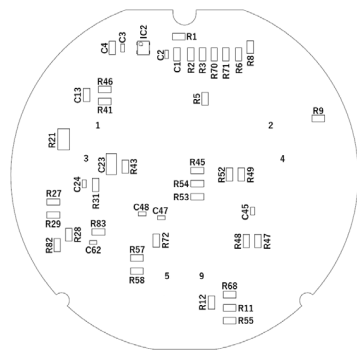
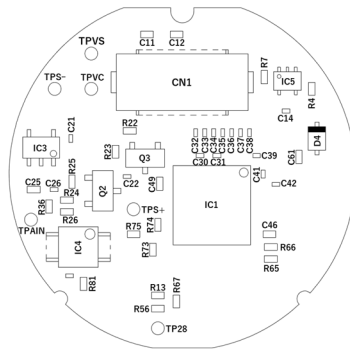
INNER LAYER
(2 LAYER)INNER LAYER
(3 LAYER)

SOLDERING SIDE

SILK PRINT FOR
SOLDEING SIDE

THROUGH HOLE

MARK	DIAGRAM	HOLE	MEMO
○	φ0.3	TH	
⊙	φ0.9	TH	
□	φ0.71	NTH	
⊠	φ2.51	NTH	

All drawings are view of parts side
SCALE 1:1PARTS NAME FOR
PARTS SIDEPARTS NAME FOR
SOLDERING SIDE

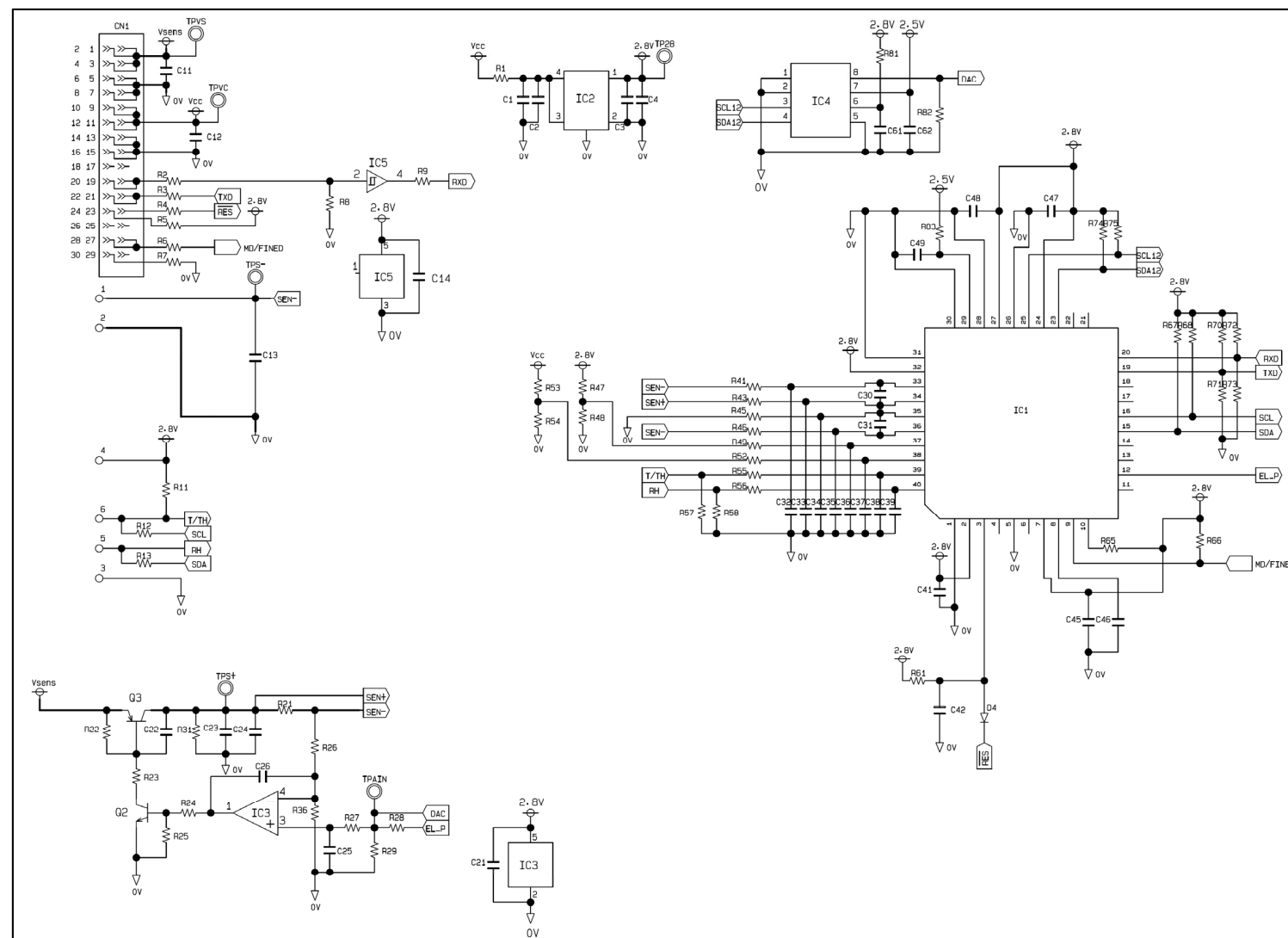
SPECIFICATION FOR PCB

- PCB No. : RKP-92786P
- Material : Glass epoxy
- Thickness : 1.2mm
- Layer number : 4
- Thickness copper film : 35um
Surface : 35um, Inner : 35um
- Minimum conductor width : 0.15mm
- CTI : 100 above

PARTS LIST

Mark of drawing	Kind of parts	Rating / Model of parts	Remarks
IC1	IC(CPU)	R5F523E6ADNF [RENESAS]	
IC2	IC(LDO)	S-1335A28-A4T2 [ABLIC]	
IC3	IC(OPAMP)	AD8538AUJZ [ANALOG DEVICES]	
IC4	IC(D/A converter)	DAC101C085C1MM [TI]	
IC5	IC(Buffer)	SN74LVC1G17DCK [TI]	
Q2	NPN Transistor	2SC2712Y(T5LTST,F) [TOSHIBA]	
Q3	NPN Transistor	NSS12200LT1G [ON Semiconductor]	
D4	Schottky Barrier Diode	1PS76SB40 [NXP]	
R1-R9,R12,R13, R22-R29,R31,R36, R41,R43,R45-R49, R52-R58,R61, R65-R68,R70-R75, R81-R83	Chip fixed resistor or Chip jumper	10ohm - 10Mohm / 1%, 0.1W or 50m ohm max,1A (1005)	
R21	Chip fixed resistor or Chip jumper	1ohm - 10Mohm / 1%, 0.1W or 50m ohm max,1A (1608)	
C1-C4,C11-C14, C21-C26,C30-C39, C41,C42,C45-C49, C61,C62	Chip multilayer capacitor	Total capacitance 38.8uFmax	

All components may be replaced with equivalent components or may not be mounted.



SCHEMATIC

注 記 NOTES		改版担当者 REV. BY	改版日 REVISED	名 称 NAME
改版回数 REV.	0	総頁数 PAGES	1	DIGITAL PCB
承認 APPROVED	検 討 CHECKED	製 図 DRAWN	作成日 DATE	図 番 DWG. NO.
北村正英	小野圭	木村司	2021.4.7	E 3 - 6 9 9 1 - 6 2 0 0 - 3 0 - 0 1 K

RIKEN KEIKI

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